

L Number	Hits	S ar h Text	DB	Time stamp
1	202	(chip sam und rfill\$3).ab.	USPAT;	2003/04/29
-	220809	integrat d adj circuit	US-P PUB	15:52
-	37514	glass adj substrate	USPAT;	2003/04/29
-	1119	(integrated adj circuit) same (glass adj substrate)	US-P PUB	09:54
-	568	laser and ((integrated adj circuit) same (glass adj substrate))	USPAT;	2003/04/28
-	58	((melt or melting or melted) with laser) and ((integrated adj circuit) same (glass adj substrate))	US-PGPUB	16:36
-	28	((melt or melting or melted) with edge) same (glass adj substrate)	USPAT;	2003/04/28
-	6	(integrated adj circuit) and (((melt or melting or melted) with edge) same (glass adj substrate))	US-PGPUB	09:45
-	27	(grinding with edge) same (glass adj substrate)	USPAT;	2003/04/28
-	378	65/61.ccls.	US-PGPUB	09:46
-	57	laser and 65/61.ccls.	USPAT;	2003/04/28
-	55	grinding and ((integrated adj circuit) same (glass adj substrate))	US-PGPUB	10:47
-	29	laser and (grinding and ((integrated adj circuit) same (glass adj substrate)))	USPAT;	2003/04/28
-	41241	glass adj substrate	US-PGPUB	10:37
-	166712	integrated adj circuit	USPAT;	2003/04/28
-	557	(glass adj substrate) and (integrated adj circuit)	US-PGPUB	10:38
-	1	laser and edge and ((glass adj substrate) and (integrated adj circuit))	USPAT;	2003/04/28
-	26	laser and ((glass adj substrate) and (integrated adj circuit))	US-PGPUB	10:46
-	14	melt\$3 and ((glass adj substrate) and (integrated adj circuit))	EPO; JPO;	2003/04/28
-	511	156/153.ccls.	DERWENT	10:46
-	744	156/155.ccls.	EPO; JPO;	2003/04/28
-	337	156/272.8.ccls.	DERWENT	10:48
-	7	156/153.ccls. and 156/272.8.ccls.	EPO; JPO;	2003/04/28
-	11	156/155.ccls. and 156/272.8.c ls.	DERWENT	10:50
			EPO; JPO;	2003/04/28
			USPAT;	11:21
			US-PGPUB	11:21
			USPAT;	2003/04/28
			US-PGPUB	11:21
			USPAT;	2003/04/28
			US-PGPUB	11:21
			USPAT;	2003/04/28
			US-PGPUB	11:22
			USPAT;	2003/04/28
			US-PGPUB	11:24

-	9	156/153.c ls. and 156/155.ccls.	USPAT; US-PGPUB	2003/04/28 11:25
-	132	(grinding with edge) and (glass adj substrate)	USPAT; US-PGPUB	2003/04/28 12:23
-	5	("4542037" "4682003" "5226101" "5582897" "5772720").PN.	USPAT	2003/04/28 12:16
-	38438	chamfer\$3	USPAT; US-PGPUB	2003/04/28 12:23
-	322	laser same chamfer\$3	USPAT; US-PGPUB	2003/04/28 12:24
-	24	(integrated adj circuit) and (laser same chamfer\$3)	USPAT; US-PGPUB	2003/04/28 12:44
-	2244	laser same grinding	USPAT; US-PGPUB	2003/04/28 12:45
-	233	(bevel\$3 or chamfer\$3) and (laser same grinding)	USPAT; US-PGPUB	2003/04/28 16:45
-	1	"5545277".PN.	USPAT	2003/04/28 15:38
-	4	5545277.URPN.	USPAT	2003/04/28 15:39
-	54008	sharp with edge	USPAT; US-PGPUB	2003/04/28 15:44
-	630	(glass adj substrate) and (sharp with edge)	USPAT; US-PGPUB	2003/04/28 16:57
-	63	(glass adj substrate) same (sharp with edge)	USPAT; US-PGPUB	2003/04/28 15:50
-	2159	(resin or adhesive) same (sharp with edge)	USPAT; US-PGPUB	2003/04/28 16:16
-	288	(TAB or TCP) and ((resin or adhesive) same (sharp with edge))	USPAT; US-PGPUB	2003/04/28 16:35
-	191	tape adj automatic adj bonding	USPAT; US-PGPUB	2003/04/28 16:18
-	44703	(adhesive or resin) with edge	USPAT; US-PGPUB	2003/04/28 16:54
-	953	(glass adj substrate) and ((adhesive or resin) with edge)	USPAT; US-PGPUB	2003/04/28 16:37
-	466	circuit and ((glass adj substrate) and ((adhesive or resin) with edge))	USPAT; US-PGPUB	2003/04/28 16:40
-	3	(ta-ko with chuang).in.	USPAT; US-PGPUB	2003/04/28 16:43
-	1	(sakae adj tanaka).in.	USPAT; US-PGPUB	2003/04/28 16:42
-	39	(sakae with tanaka).in.	USPAT; US-PGPUB	2003/04/28 16:43
-	3	(ta-ko with chuang).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/28 16:43
-	228	(sakae with tanaka).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/28 16:44

-	686	(b v l\$3 or chamf r\$3) ame ((adh siv r r in) with edg)	USPAT; US-P PUB	2003/04/28 16:47
-	26	(glass adj sub trat) and ((bevel\$3 or chamf r\$3) same ((adh sive or r sin) with edge))	USPAT; US-P PUB	2003/04/28 16:54
-	289	(adh sive or r sin) with dg with protection	USPAT; US-PGPUB	2003/04/28 16:55
-	19	(glass adj substrate) and ((adhesive or resin) with edge with protection)	USPAT; US-PGPUB	2003/04/28 17:12
-	82	(protecting adj circuit) and (external adj circuit)	USPAT; US-PGPUB	2003/04/28 17:23
-	6	(edge same substrate) and ((protecting adj circuit) and (external adj circuit))	USPAT; US-PGPUB	2003/04/28 17:24
-	9556	uv adj (cured or curable or curing)	USPAT; US-PGPUB	2003/04/28 17:24
-	2785	circuit and (uv adj (cured or curable or curing))	USPAT; US-PGPUB	2003/04/28 17:25
-	802	(integrated adj circuit) and (uv adj (cured or curable or curing))	USPAT; US-PGPUB	2003/04/28 17:26
-	118	(cover\$3 same edge) and ((integrated adj circuit) and (uv adj (cured or curable or curing)))	USPAT; US-PGPUB	2003/04/28 17:27
-	14	((edge or corner) with protection) same (glass adj substrate)	USPAT; US-PGPUB	2003/04/29 10:04
-	832	(melt\$3 same (glass adj substrate)) and circuit	USPAT; US-PGPUB	2003/04/29 10:07
-	245	(melt\$3 same (glass adj substrate)) and (integrated adj circuit)	USPAT; US-PGPUB	2003/04/29 10:08
-	49	(melt\$3 same (glass adj substrate)) and ((integrated adj circuit) same bond\$3)	USPAT; US-PGPUB	2003/04/29 10:08